# OSRAM LB Q99G.01 **Datasheet**



## Chip LED 0603

# LB Q99G.01

The square package with just 2mm outline combines best performance with a small footprint for environments where improved corrosion robustness is needed. A centralized chip allows an easy integration into optical systems. The availability of all main colors and white points gives highest flexibility in various application areas.







## **Applications**

- Appliances & Tools
- Display Backlighting
- Factory Automation
- Home & Building Automation

- Projection & Display
- Static Signaling
- Transportation

#### **Features**

- Package: SMT package 0603, clear epoxy

- Chip technology: InGaN on Sapphire

- Typ. Radiation: 150°

- Color:  $\lambda_{dom}$  = 470 nm (• blue)

- Corrosion Robustness Class: 2B

- ESD: 1 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM)



## **Ordering Information**

Ordering Code Type Luminous Intensity 1)

 $I_F = 5 \text{ mA}$ 

45.0 ... 140.0 mcd LB Q99G.01-P1R1-35-1 Q65113A5255



Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T <sub>op</sub>	min.	-40 °C
		max.	85 °C
Storage Temperature	$T_{stg}$	min.	-40 °C
		max.	85 °C
Junction Temperature	$T_{j}$	max.	95 °C
Forward current	I <sub>F</sub>	min.	1 mA
$T_S = 25  ^{\circ}C$	·	max.	20 mA
Forward Current pulsed	   F pulse	max.	100 mA
$t \le 100 \ \mu s; \ D = 0.03 \ ; \ T_s = 25 \ ^{\circ}C$	,,,,,		
Surge Current	I <sub>FS</sub>	max.	100 mA
$t \le 10 \ \mu s; \ D = 0.005; \ T_s = 25 \ ^{\circ}C$			
Reverse voltage 2)	$V_R$	max.	5 V
$T_S = 25  ^{\circ}C$	K		
ESD withstand voltage	$V_{ESD}$		1 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM)	200		



#### **Characteristics**

 $I_F = 5$  mA;  $T_S = 25$  °C

Parameter	Symbol		Values
Peak Wavelength	$\lambda_{peak}$	typ.	466 nm
Dominant Wavelength 3)	$\lambda_{\sf dom}$	min.	464 nm
	40	typ.	470 nm
		max.	476 nm
Spectral Bandwidth at 50% I <sub>rel,max</sub>	Δλ	typ.	22 nm
Viewing angle at 50% $\rm I_{\rm v}$	2φ	typ.	140 °
Forward Voltage 4)	$V_{F}$	min.	2.60 V
$I_{\rm F} = 5  \text{mA}$		typ.	2.85 V
		max.	3.10 V
Reverse current 2)	I <sub>R</sub>	typ.	0.01 μΑ
$V_R = 5 V$	TX.	max.	10 µA
Real thermal resistance junction/solderpoint 5)	R <sub>thJS real</sub>	typ.	410 K / W
	uioo reai	max.	500 K / W



## **Brightness Groups**

Group	Luminous Intensity 1)	Luminous Intensity. 1)	Luminous Flux 6)
	$I_F = 5 \text{ mA}$	$I_F = 5 \text{ mA}$	$I_F = 5 \text{ mA}$
	min.	max.	typ.
	$I_{v}$	$I_{v}$	$\Phi_{V}$
P1	45.0 mcd	56.0 mcd	212.1 mlm
P2	56.0 mcd	71.0 mcd	266.7 mlm
Q1	71.0 mcd	90.0 mcd	338.1 mlm
Q2	90.0 mcd	112.0 mcd	424.2 mlm
R1	112.0 mcd	140.0 mcd	529.2 mlm

# **Forward Voltage Groups**

Group	Forward Voltage <sup>4)</sup> I <sub>F</sub> = 5 mA min. V <sub>F</sub>	Forward Voltage <sup>4)</sup> I <sub>F</sub> = 5 mA max. V <sub>F</sub>	
3X	2.60 V	2.70 V	
3Y	2.70 V	2.80 V	
3Z	2.80 V	2.90 V	
4X	2.90 V	3.00 V	
4Y	3.00 V	3.10 V	

# **Wavelength Groups**

Group	Dominant Wavelength 3)	Dominant Wavelength 3)	
	min.	max.	
	$\lambda_{\sf dom}$	$\lambda_{\sf dom}$	
3	464 nm	468 nm	
4	468 nm	472 nm	
5	472 nm	476 nm	

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## **Group Name on Label**

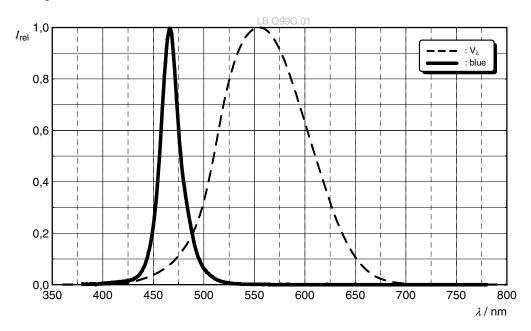
Example: P1-3-3X

Brightness	Wavelength	Forward Voltage	
P1	3	3X	



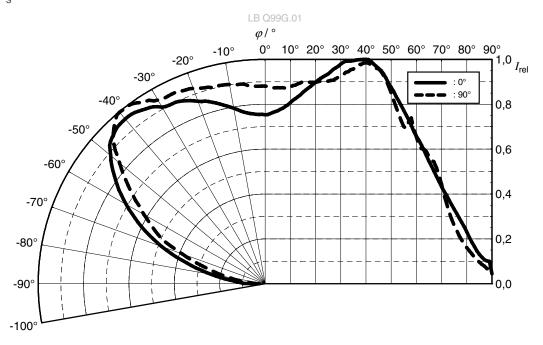
#### Relative Spectral Emission 6)

$$I_{rel}$$
 = f ( $\lambda$ );  $I_F$  = 5 mA;  $T_S$  = 25 °C



#### Radiation Characteristics 6)

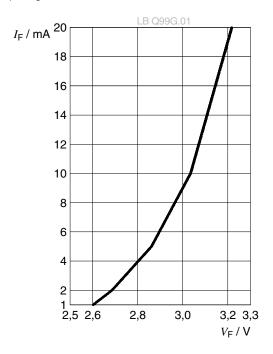
$$I_{rel} = f(\phi); T_S = 25 °C$$





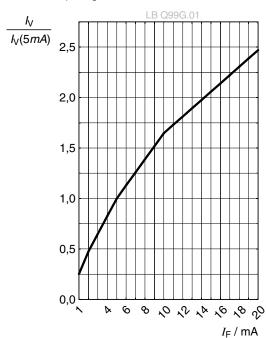
#### Forward current 6)

$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



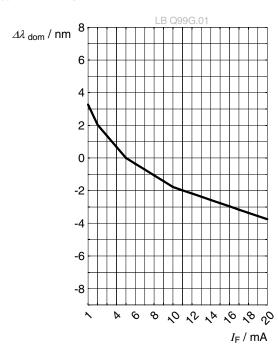
## Relative Luminous Intensity 6), 7)

$$I_{v}/I_{v}(5 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$$



## **Dominant Wavelength** 6)

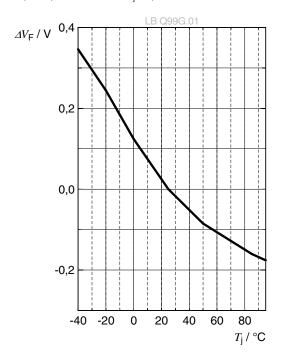
$$\Delta\lambda_{dom} = f(I_F); T_S = 25 \, ^{\circ}C$$





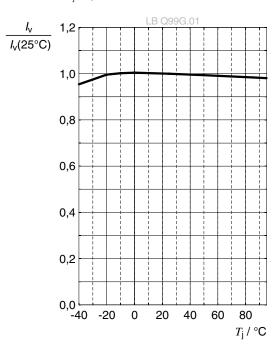
#### Forward Voltage 6)

$$\Delta V_F = V_F - V_F (25 \, ^{\circ}C) = f(T_j); I_F = 5 \, \text{mA}$$



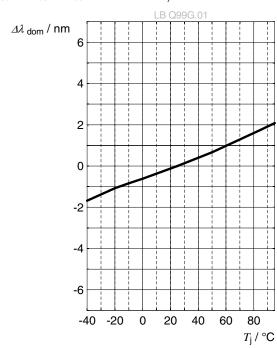
## Relative Luminous Intensity 6)

$$I_{v}/I_{v}(25 \text{ °C}) = f(T_{i}); I_{F} = 5 \text{ mA}$$



## Dominant Wavelength 6)

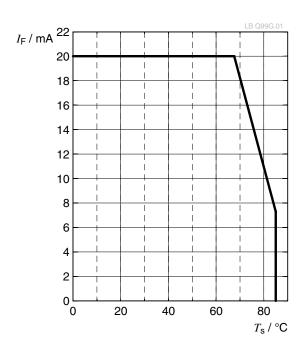
$$\Delta \lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}} (25 \ ^{\circ}\text{C}) = f(T_j); \ I_F = 5 \ \text{mA}$$





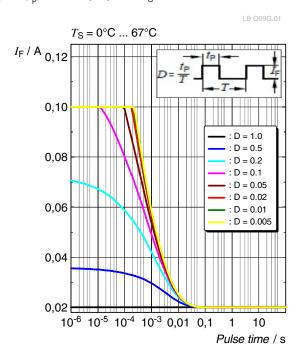
#### Max. Permissible Forward Current

 $I_{\scriptscriptstyle F} = f(T)$ 



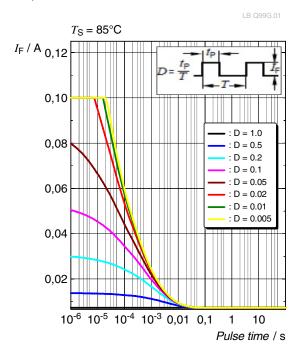
## Permissible Pulse Handling Capability

 $I_F = f(t_p)$ ; D: Duty cycle;  $T_S = 25 \,^{\circ}\text{C}$ 



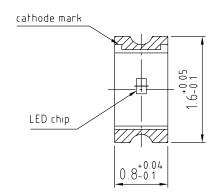
#### Permissible Pulse Handling Capability

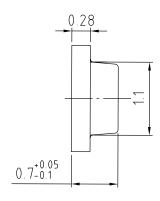
 $I_F = f(t_p)$ ; D: Duty cycle;  $T_S = 85$  °C

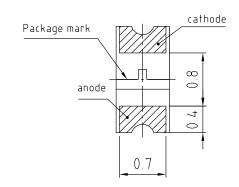




## **Dimensional Drawing** 8)







general tolerance  $\pm 0.1$ 

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lead finish Ag

#### **Further Information:**

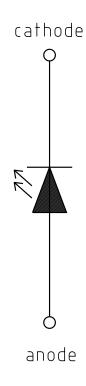
**Approximate Weight:** 1.4 mg

**Corrosion test:** Class: 2B

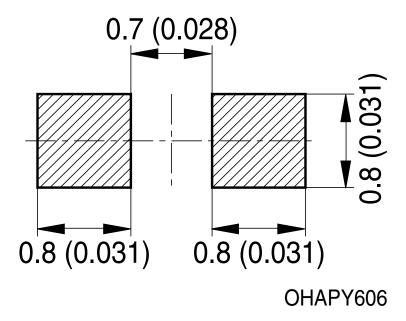
Test condition:  $25^{\circ}$ C / 75 % RH / 10 ppm H<sub>2</sub>S / 21 days (IEC 60068-2-43)



#### **Electrical Internal Circuit**



#### Recommended Solder Pad 8)

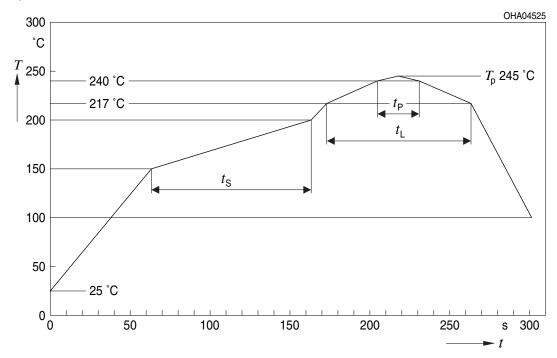


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



#### **Reflow Soldering Profile**

Product complies to MSL Level 3 acc. to JEDEC J-STD-020E



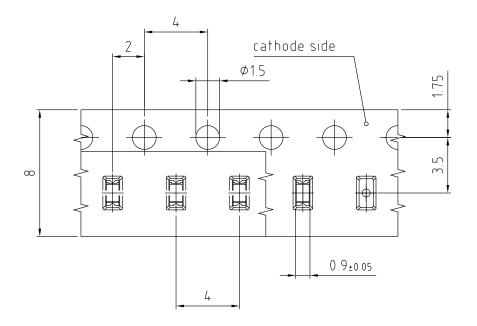
Profile Feature	Symbol	Pb	-Free (SnAgCu) Ass	sembly	Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t <sub>s</sub> T <sub>Smin</sub> to T <sub>Smax</sub>	t <sub>s</sub>	60	100	120	S
Ramp-up rate to peak*) $T_{Smax}$ to $T_{P}$			2	3	K/s
Liquidus temperature	$T_{L}$		217		°C
Time above liquidus temperature	t <sub>L</sub>		80	100	S
Peak temperature	T <sub>P</sub>		245	260	°C
Time within 5 °C of the specified peak temperature T <sub>P</sub> - 5 K	t <sub>P</sub>	10	20	30	S
Ramp-down rate* T <sub>P</sub> to 100 °C			3	6	K/s
Time 25 °C to T <sub>P</sub>				480	S

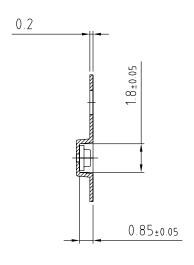
All temperatures refer to the center of the package, measured on the top of the component

<sup>\*</sup> slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



# Taping 8)

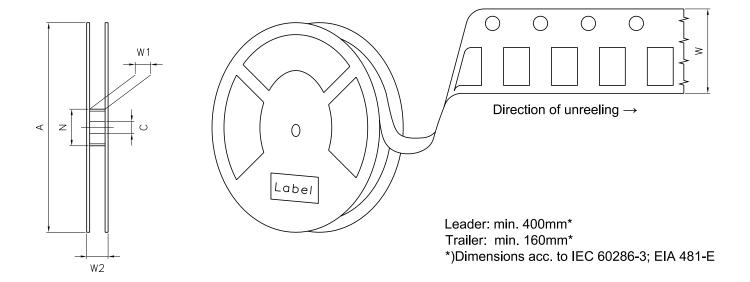




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## Tape and Reel 9)

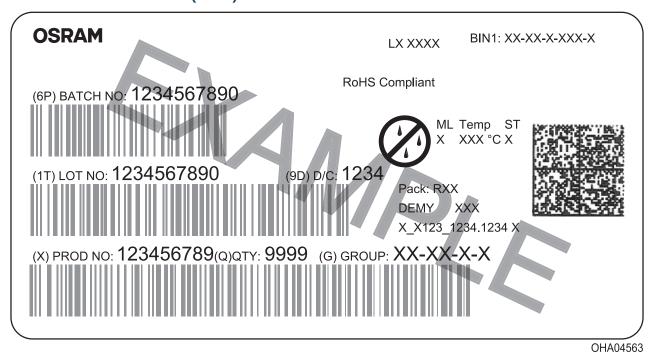


#### **Reel Dimensions**

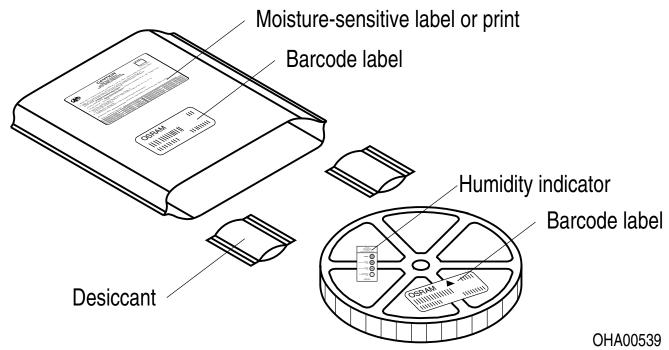
Α	W	$N_{\min}$	$W_1$	$W_{2 max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	58 mm	8.4 + 1,5 mm	14.4 mm	4000



#### **Barcode-Product-Label (BPL)**



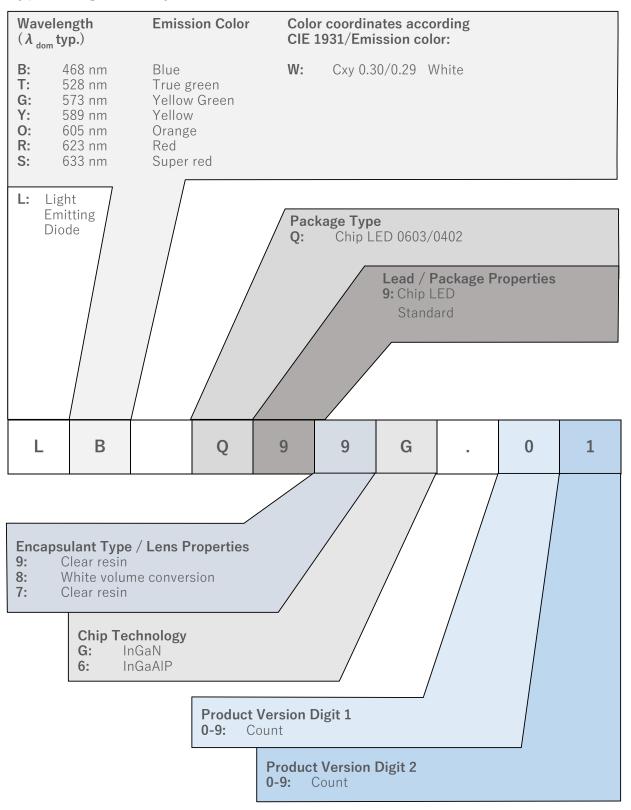
## Dry Packing Process and Materials 8)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



#### **Type Designation System**





#### **Notes**

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class exempt group (exposure time 10000 s). Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



#### Disclaimer

#### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

#### **Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

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Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.



#### Glossary

- Brightness: Brightness groups are tested at a current pulse duration of 25 ms and a tolerance of ±11 %.
- 2) Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- 3) Wavelength: Wavelengths are tested at a current pulse duration of 25 ms and a tolerance of ±1 nm.
- 4) Forward Voltage: Forward voltages are tested at a current pulse duration of 1 ms and a tolerance of ±0.1 V.
- 5) **Thermal Resistance:** Rth max is based on statistic values  $(6\sigma)$ .
- 6) Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- 9) Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

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#### **Revision History**

Version	Date	Change
1.0	2023-02-09	Initial Version



EU RoHS and China RoHS compliant product 此产品符合欧盟 RoHS 指令的要求; 按照中国的相关法规和标准, 不含有毒有害物质或元素。

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